





	LAA110	Units
Load Voltage	350	V
Load Current	120	mA
Max R _{ON}	35	Ω

Features

- Small 8 Pin DIP Package
- Low Drive Power Requirements (TTL/CMOS Compatible)
- · No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- 3750V_{RMS} Input/Output Isolation
- FCC Compatible
- VDE Compatible
- No EMI/RFI Generation
- · Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available

Applications

- Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hookswitch
 - Dial Pulsing
 - Ground Start
 - · Ringer Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - · Electronic Switching
 - I/O Subsystems
 - Meters (Watt-Hour, Water, Gas)
 - Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- · Industrial Controls

Description

LAA110 is a Dual 1 Form-A solid state relay that has two independently controlled optically coupled MOSFETs. The efficient MOSFET switches and photovoltaic die use Clare's patented OptoMOS® architecture to provide 3750 $V_{\rm RMS}$ of input to output isolation. The optically coupled inputs are controlled by highly efficient GaAlAs infrared LEDs. Dual pole OptoMOS relays provide a more compact design solution than discrete single pole relays in a variety of applications. The dual pole relays save board space by incorporating both relays in a single 8-pin package.

Approvals

- UL Recognized: File Number E76270
- CSA Certified: File Number LR 43639-10
- · BSI Certified to:
 - BS EN 60950:1992 (BS7002:1992)

Certificate #: 7344

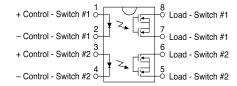
BS EN 41003:1993
Certificate #: 7344

Ordering Information

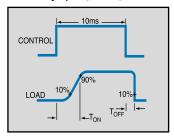
Part #	Description
LAA110	8 Pin DIP (50/Tube)
LAA110P	8 Pin Flatpack (50/Tube)
LAA110PTR	8 Pin Flatpack (1000/Reel)
LAA110S	8 Pin Surface Mount (50/Tube)
LAA110STR	8 Pin Surface Mount (1000/Reel)

Pin Configuration

LAA110 Pinout



Switching Charcteristics of Normally Open (Form A) Devices





Absolute Maximum Ratings (@ 25° C)

Parameter	Min	Тур	Max	Units
Input Power Dissipation	-	-	150 ¹	mW
Input Control Current	-	-	50	mA
Peak (10ms)	-	-	1	Α
Reverse Input Voltage	-	-	5	V
Total Power Dissipation	-	-	800 ²	mW
Isolation Voltage				
Input to Output	3750	-	-	V_{RMS}
Operational Temperature	-40	-	+85	°C
Storage Temperature	-40	-	+125	°C
Soldering Temperature				
(10 Seconds Max.)				
DIP Package	-	-	+260	°C
Flatpack/Surface Mount				
Package	-	-	+220	°C

excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and effect its reliability.

Absolute Maximum Ratings are stress ratings. Stresses in

Electrical Characteristics

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics @ 25°C						
Load Voltage (Peak)	-	V_{L}	-	-	350	V
Load Current (Continuous)*	-	I,	-	-	120	mA
Peak Load Current	10ms max	I _{LPK}	-	-	350	mA
On-Resistance	I _I =120mA	R _{on}	-	25	35	Ω
Off-State Leakage Current	V _I =350V	I _{LEAK}	-	-	1	μΑ
Switching Speeds	_					
Turn-On	I _F =5mA, V _L =10V	T_{ON}	-	-	3	ms
Turn-Off	I _F =5mA, V _L =10V	T_{OFF}	-	-	3	ms
Output Capacitance	50V; f=1MHz	C _{OUT}	-	25	-	pF
Input Characteristics @ 25°C						
Input Control Current	I _I =120mA	l _e	5	-	50	mA
Input Dropout Current	-	-	0.4	0.7	-	mA
Input Voltage Drop	I _F =5mA	V_{F}	0.9	1.2	1.4	V
Reverse Input Voltage	-	V _R	-	-	5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF
Input to Output Isolation	-	V _{I/O}	3750	-	-	V_{RMS}

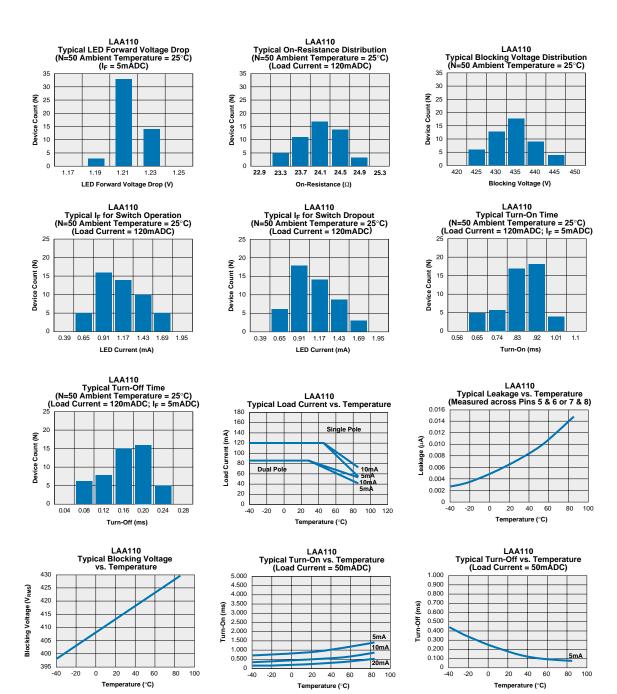
^{*}Note: If both poles operate load current must be derated so as not to exceed the package power dissipation valve.

¹ Derate Linearly 1.33 mw/⁻C

² Derate Linearly 6.67 mw/°C

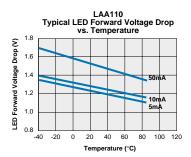


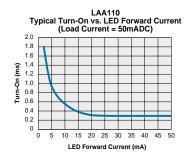
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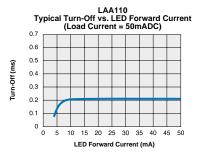


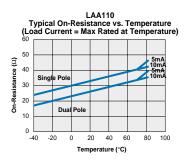


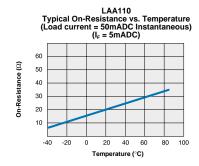
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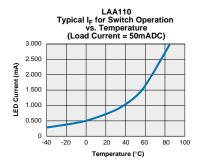


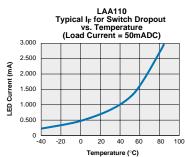


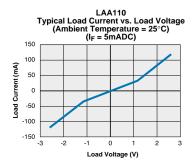


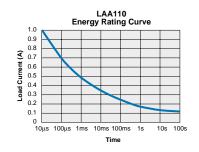








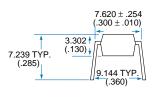


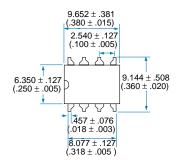




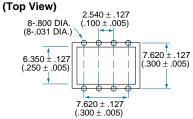
Mechanical Dimensions

8 Pin DIP Through Hole (Standard)

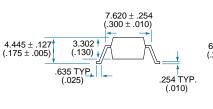


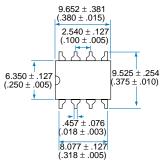


PC Board Pattern

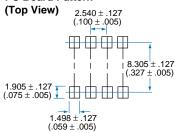


8 Pin DIP Surface Mount ("S" Suffix)

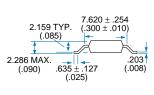


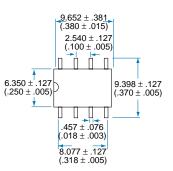


PC Board Pattern

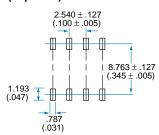


8 Pin Flatpack ("P" Suffix)





PC Board Pattern (Top View)



Dimensions mm (inches)



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